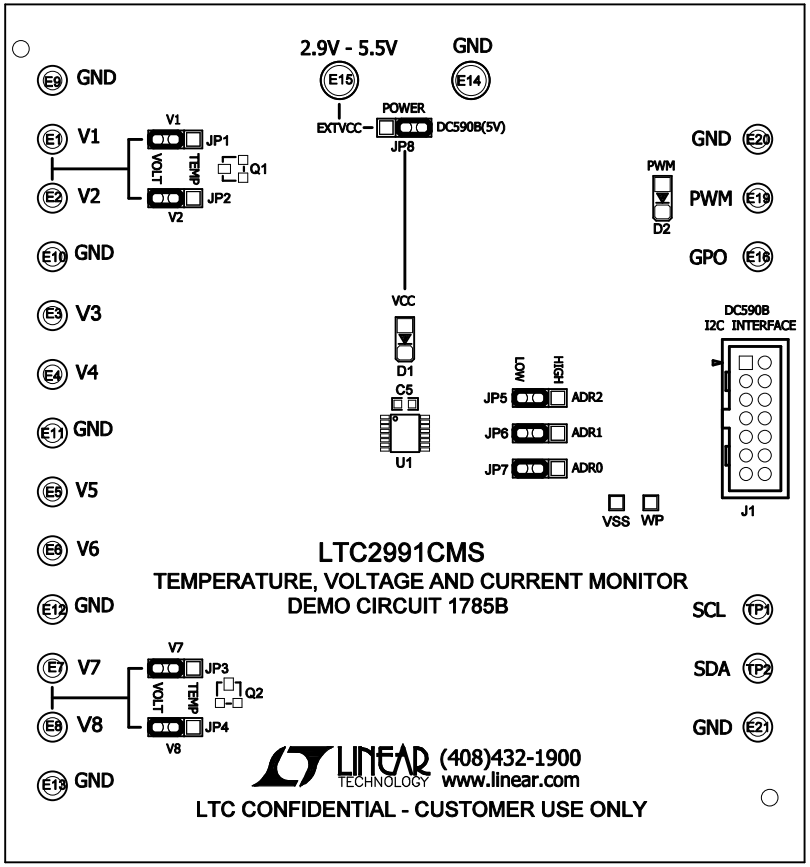
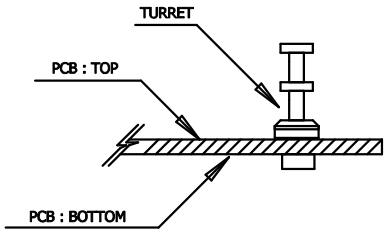
REVISION HISTORY				
ECO	REV	DESCRIPTION	APPR	DATE
-	B	PRODUCTION	LEO C	Apr 09, 2014



NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP AND BOTTOM SIDE SMD. MAXIMUM SOLDER TEMPERATURE IS 240 DEG. C.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. INSTALL SHUNTS AS SHOWN ON ASSY DRAWING.
5. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
6. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD.
7. INSTALL TURRETS AS SHOWN BELOW:



8. NOTE POLARITY: D1 AND D2.

APPROVALS	
PCB DES.	RB
APP ENG.	LEO CHEN
SCALE = NONE	

LINEAR TECHNOLOGY
1630 MCCARTHY BLVD
MILPITAS, CA 95035
PH: (408)432-1900
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TITLE: TOP ASSEMBLY DRAWING
TEMPERATURE, VOLTAGE AND CURRENT MONITOR

SIZE	IC NO.	REV.
N/A	LTC2991CMS DEMO CIRCUIT 1785B	1

FILENAME: 1785B_Rev1.PCB | SHT 1 OF 2